GP1UE26XK/GP1UE27XK Series GP1UE28XK/GP1UE28YK Series

■ Features

- 1. Low dissipation current:MAX. 0.6mA(at V_{CC}=3V)
- 2. Low operating voltage: 2.4 to 3.6V
- 3. Compact (case volume).
- 4. Various B.P.F. (Band Pass Frequency) frequency to meet different user needs.

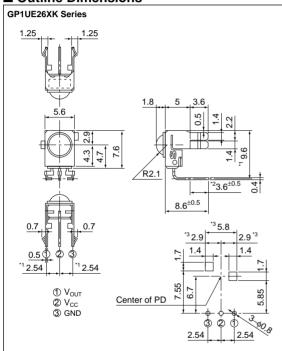
Low Voltage Operation, **Compact IR Detecting Unit** for Remote Control

■ Applications

- 1. AV equipments
- 2. Home appliances

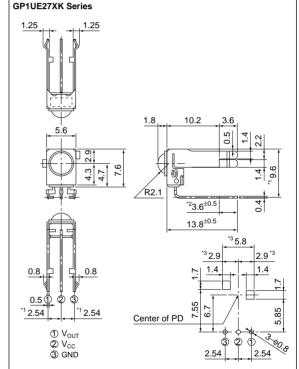
■ Outline Dimensions

(Unit: mm)



Example of mounting drawing from solder side (Reference)

- 1.*1: Indicates root dimensions of connector.
- 2.Unspecified tolerance: ±0.3
- 3.Case thickness: 0.3TYP
- 4.*2 : Exclude sagged solder
- 5.*3: If there are difficulties to insert the GP1UE26XK series on PCB, we recommend to expand +0.1mm from original 2.9mm.



Example of mounting drawing from solder side (Reference)

- 1.*1: Indicates root dimensions of connector. 2.Unspecified tolerance: ±0.3
- 3.Case thickness: 0.3TYP
- 4.*2 : Exclude sagged solder
- 5.*3: If there are difficulties to insert the GP1UE27XK series on PCB, we recommend to expand +0.1mm from original 2.9mm.

from solder side (Reference)

1.4

³2.9

Top of lenz

■ Outline Dimensions (Unit: mm) **GP1UE28XK Series GP1UE28YK Series** 1.25 1.25 2.75 1.8 R2.1 14.2 3.6 1.8 0.5 8.0 0.4 *11.7 ζi, ① V_{OUT} 9.6 3.7 1.4 0.8 ② V_{cc} 3 GND 5.4 R2.1 1.4 6.8 *12.54 *23.6^{±0.5} 0.4 17.8^{±0.5} Example of mounting drawing

1.*1 : Indicates root dimensions of connector.

2.54

① V_{OUT} ② V_{CC}

3 GND

Example of mounting drawing

from solder side (Reference)

2.9 *3

1.4

2.54

- 2.Unspecified tolerance: ±0.3
- 3.Case thickness : 0.3TYP

0.8

0.5

*1 2.54

- 4.*2 : Exclude sagged solder
- 5.*3: If there are difficulties to insert the **GP1UE28XK** series on PCB, we recommend to expand +0.1mm from original 2.9mm.

Center of PD

7.55

- 1.*1: Indicates root dimensions of connector.
- 2.Unspecified tolerance: ±0.3 3.Case thickness: 0.3TYP
- 4.*2 : Exclude sagged solder
- 5.*3: If there are difficulties to insert the **GP1UE28YK** series on PCB, we recommend to expand +0.1mm from original 2.9mm.

1.4

*32.9

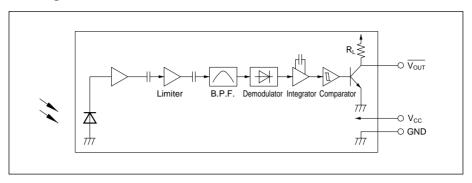
^{*3}5.8

■ Model Line-up

Diversified models with a different B.P.F. frequency are also available.

B.P.F. center frequency	Model No.				Unit
40	GP1UE26XK	GP1UE27XK	GP1UE28XK	GP1UE28YK	
36	GP1UE260XK	GP1UE270XK	GP1UE280XK	GP1UE280YK	
38	GP1UE261XK	GP1UE271XK	GP1UE281XK	GP1UE281YK	kHz
36.7	GP1UE262XK	GP1UE272XK	GP1UE282XK	GP1UE282YK	
56.8	GP1UE267XK	GP1UE277XK	GP1UE287XK	GP1UE287YK	

■ Internal Block Diagram



■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	0 to +6.0	V
*1 Operating temperature	T_{opr}	-10 to +70	°C
Storage temperature	T_{stg}	-20 to +70	°C
*2 Soldering temperature	T _{sol}	260	°C

^{*1} No dew condensation is allowed

■ Recommended Operating Conditions

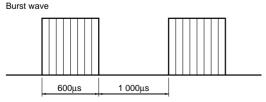
Parameter		Symbol Operating conditions		Unit	
Supply voltage		V_{CC}	2.4 to 3.6	V	

■ Electro-optical Characteristics

 $(T_a=25^{\circ}C, V_{CC}=3V)$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Dissipation current	I_{CC}	No input light	-	0.4	0.6	mA
High level output voltage	V_{OH}	*3	V _{CC} -0.5	_	_	V
Low level output voltage	V_{OL}	*3 I _{OL} =1.6mA	-	_	0.45	V
High level pulse width	T_1	*3	600	_	1 200	μs
Low level pulse width	T_2	*3	400	-	1 000	μs
B.P.F. center frequency	f_0	+	-	*4	_	kHz
Output pull-up resistance	R_L	1	70	100	130	kΩ

^{*3} The burst wave as shown in the following figure shall be transmitted by the transmitter shown in Fig. 1



f₀=(*4) Duty 50%

^{*2} For 5s (At mounting on PCB with thickness of 1.6mm)

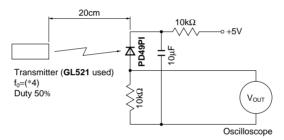
The carrier frequency of the transmitter, however, shall be same as *4, and measurement shall be from just after starting the transmission until 50 pulse *4 The B.P.F. center frequency f_0 varies with model, as shown in **Model Line-up**

■ Performance

Using the transmitter shown in Fig. 1, the output signal of the light detecting unit is good enough to meet the following items in the standard optical system in Fig. 2.

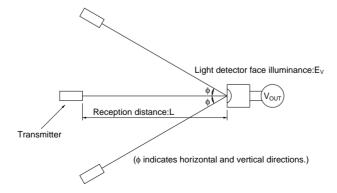
- 1. Linear reception distance characteristics
 - When L=0.2 to $10.0(8.0)^{*7}$ m, *5 E $_{V}$ <10 lx and ϕ =0° in Fig.2, the output signal shall meet the electrical characteristics in the attached list.
- 2. Sensitivity angle reception distance characteristics
 - When L=0.2 to $7.5(6.0)^{*7}$ m, $*^{5}$ E $_{V}$ <10 lx and ϕ ≤30° in Fig.2, the output signal shall meet the electrical characteristics in the attached list.
- 3. Anti outer peripheral light reception distance characteristics
 - When L=0.2 to $5.0(4.0)^{*7}$ m, ${}^{*6}E_{V} \le 300$ lx and $\phi = 0^{\circ}$ in Fig.2, the output signal shall meet the electrical characteristics in the attached list.

Fig.1 Transmitter



In the above figure, the transmitter should be set so that the output $V_{OUT\,(P\cdot P)}$ can be 40mV. However, the **PD49PI** to be used here should be of the short-circuit current I_{SC} =2.6 μ A at E_V =100 lx. (E_V is an illuminance by CIE standard light source A (tungsten lamp).)

Fig.2 Standard Optical System



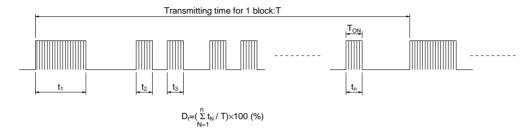
^{*5} It refers to detector face illuminance

^{*6} Outer peripheral light source: CIE standard light source A shall be used and placed at 45° from perpendicular axis at the detector face center

^{*7} In case of B.P.F. center frequency: 56.8kHz model

■ Precautions for Operation

1. When this infrared remote control detecting unit shall be adopted for wireless remote control, please use it with the signal format of transmitter, which total duty ratio D_t (Emitting time $\sum_{N=1}^{n} t_N$ / Transmitting time for 1 block T) is 40% or less. ON signal time T_{ON} (Pulse width of the presence of modulated IR) should be 250(200:In case of B.P.F center frequency:56.8kHz model) μ s or more. In case that the signal format of total duty and ON signal time is out of above conditions, there is a case that reception distance is much reduced or output is not appeared.



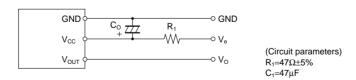
- 2. Use the light emitting unit (remote control transmitter), in consideration of performance, characteristics, operating conditions of light emitting device and the characteristics of the light detecting unit.
- 3. Pay attention to a malfunction of the light detecting unit when the surface is stained with dust and refuse.

Care must be taken not to touch the light detector surface.

If it should be dirty, wipe off such dust and refuse with soft cloth so as to prevent scratch. In case some solvents are required, use methyl alcohol, ethyl alcohol or isopropyl alcohol only.

Also, protect the light detecting unit against flux and others, since their deposition on the unit inside causes reduction of the function, fading of markings such as the part number.

- 4. The shield case should be grounded on PCB pattern.
 - (The area across the shield case and the GND terminal is internally conductive in some cases and non-conductive in some other cases.)
- 5. Do not apply unnecessary force to the terminal and the case.
- 6. Do not push the light detector surface (photodiode) from outside.
- 7. To avoid the electrostatic breakdown of IC, handle the unit under the condition of grounding with human body, soldering iron, etc.
- 8. Do not use hole and groove set in the case of the light detecting unit for other purposes, since they are required to maintain the specified performance.
- 9. External Circuit Examples (Mount the outer parts as near the unit as possible).



In setting R_1 and C_1 , use suitable values after considering under the real condition

The circuit constant is a example. It is difference from mounting equipment. Please select it by your mounting equipment.

This device has a transistor as protection element between V_{CC} and GND to improve anti-static electricity proof.

Please be carefully not to apply exceeding the absolute maximum ratings of applying voltage and continuous high voltage spike noise because there is cases that transistor will be short by secondary breakdown generally. In order to do difficultly, Please add CR filter($47\Omega(1/10W)$, $10\mu F$ or more)such as external circuit example above near V_{CC} .

- 10. There is a possibility that noise on output may be caused by environmental condition (Disturbing light noise, Electromagnetic noise, Power supply line noise, etc.) even if there is no input transmission signal.
- 11. Please shall confirm operation or your actual machine. Because the output pulse width of this product is fluctuated by environmental conditions such as signal format, temperature, distance from transmitter, and so on.
- 12. In case that this product is kept in high humidity condition, it may be hard to solder, please be careful enough about storage method.
 - Depend on the flux you select, there are different solderabilities, so please select a suitable flux and use it.
- 13. Please use this device away from the dew drop.
 - Be aware that the dew drop rusts shield case and others, may affect the electric characteristics.

NOTICE

- The circuit application examples in this publication are provided to explain representative applications of SHARP
 devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes
 no responsibility for any problems related to any intellectual property right of a third party resulting from the use of
 SHARP's devices.
- Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP
 reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents
 described herein at any time without notice in order to improve design or reliability. Manufacturing locations are
 also subject to change without notice.
- Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage
 caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used
 specified in the relevant specification sheet nor meet the following conditions:
 - (i) The devices in this publication are designed for use in general electronic equipment designs such as:
 - --- Personal computers
 - --- Office automation equipment
 - --- Telecommunication equipment [terminal]
 - --- Test and measurement equipment
 - --- Industrial control
 - --- Audio visual equipment
 - --- Consumer electronics
 - (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
 - --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
 - --- Traffic signals
 - --- Gas leakage sensor breakers
 - --- Alarm equipment
 - --- Various safety devices, etc.
 - (iii)SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
 - --- Space applications
 - --- Telecommunication equipment [trunk lines]
 - --- Nuclear power control equipment
 - --- Medical and other life support equipment (e.g., scuba).
- If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Law of Japan, it is necessary to obtain approval to export such SHARP devices.
- This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.
- Contact and consult with a SHARP representative if there are any questions about the contents of this publication.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина,

дом 2, корпус 4, литера А.